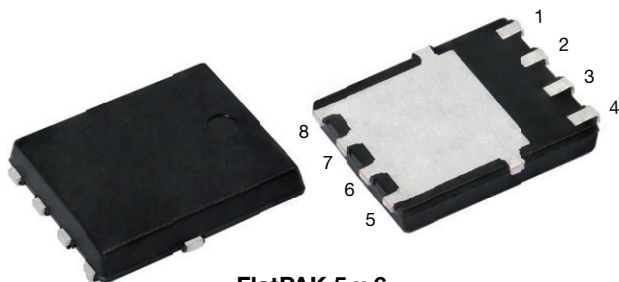
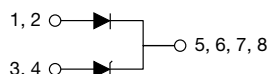


Two-in-One Solution Surface-Mount


FlatPAK 5 x 6


LINKS TO ADDITIONAL RESOURCES



FEATURES

- Automotive two-in-one solution for rectifier and TRANSZORB® TVS
- Oxide planar chip junction
- Meets MSL level 1, per J-STD-020, LF maximum peak of 260 °C
- AEC-Q101 qualified available
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912



RoHS
COMPLIANT
HALOGEN
FREE

TYPICAL APPLICATIONS

Secondary protection for sensor units, distributed airbag modules and low power DC / DC converters under power distributor

MECHANICAL DATA

Case: FlatPAK 5 x 6

Molding compound meets UL 94 V-0 flammability rating

Base P/NHM3 - halogen-free, RoHS-compliant, and AEC-Q101 qualified

Terminals: matte tin plated leads, solderable per J-STD-002 and JESD 22-B102

HM3 suffix meets JESD 201 class 2 whisker test

PRIMARY CHARACTERISTICS

| | | |
|-------------------------------|---|--------|
| Standard Rectifier | $I_{F(AV)}$ | 3 A |
| | V_{RRM} | 600 V |
| | I_{FSM} | 40 A |
| | V_F at $I_F = 3A$ ($T_J = 125\text{ °C}$) | 0.86 V |
| Transient Voltage Suppressors | V_{BR} | 27 V |
| | V_{WM} | 23.1 V |
| | P_{PPM} | 200 W |
| T_J max. | 175 °C | |
| Package | FlatPAK 5 x 6 | |
| Circuit configuration | Common cathode | |

MAXIMUM RATINGS ($T_A = 25\text{ °C}$ unless otherwise noted)

| TECHNOLOGY | PARAMETER | SYMBOL | R3T2FPHM3 | UNIT |
|--------------------------------------|--|----------------------|-------------|------|
| | Device marking code | | R3T2FP | |
| Standard Rectifier | Maximum repetitive peak reverse voltage | V_{RRM} | 600 | V |
| | Maximum DC forward current | $I_{F(AV)}^{(1)}$ | 3 | A |
| | | $I_{F(AV)}^{(2)}$ | 2 | |
| | Peak forward surge current 8.3 ms single half sine-wave superimposed on rated load per diode | I_{FSM} | 40 | A |
| Transient Voltage Suppressors | Peak pulse power dissipation with a 10/1000 μ s waveform ⁽³⁾ | P_{PPM} | 200 | W |
| | Peak pulse current with a 10/1000 μ s waveform ⁽³⁾ | I_{PPM} | 5.3 | A |
| Operating junction temperature range | | T_J ⁽⁴⁾ | -55 to +175 | °C |
| Storage temperature range | | T_{STG} | -55 to +175 | °C |

Notes

- Mounted on 3 x 3 cm aluminum pad area
- Free air mounted on recommended pad area
- Non-repetitive current pulse per Fig.10 and derated above $T_A = 25\text{ °C}$ per Fig.8
- The heat generated must be less than the thermal conductivity from junction-to-ambient: $dP_D/dT_J < 1/R_{\theta JA}$



| ELECTRICAL CHARACTERISTICS ($T_J = 25\text{ }^{\circ}\text{C}$ unless otherwise noted) | | | | | | | |
|---|----------------------------------|--|-------------------------------------|-------------|------|------|-------------------|
| TECHNOLOGY | PARAMETER | TEST CONDITIONS | | SYMBOL | MIN. | TYP. | MAX. UNIT |
| Standard Rectifier | Instantaneous forward voltage | $I_F = 1.5\text{ A}$ | $T_J = 25\text{ }^{\circ}\text{C}$ | $V_F^{(1)}$ | - | 0.91 | - V |
| | | $I_F = 3\text{ A}$ | $T_J = 25\text{ }^{\circ}\text{C}$ | | - | 0.97 | 1.1 |
| | | $I_F = 1.5\text{ A}$ | $T_J = 125\text{ }^{\circ}\text{C}$ | | - | 0.79 | - |
| | | $I_F = 3\text{ A}$ | $T_J = 125\text{ }^{\circ}\text{C}$ | | - | 0.86 | 0.98 |
| | Reverse current | Rated V_R | $T_J = 25\text{ }^{\circ}\text{C}$ | $I_R^{(2)}$ | - | - | 10 μA |
| | | | $T_J = 125\text{ }^{\circ}\text{C}$ | | - | 13 | 100 |
| | Typical reverse recovery time | $I_F = 0.5\text{ A}$, $I_R = 1.0\text{ A}$, $I_{rr} = 0.25\text{ A}$ | | t_{rr} | - | 1.5 | - μs |
| Transient Voltage Suppressors | Typical junction capacitance | 4.0 V, 1 MHz | | C_J | - | 19 | - pF |
| | Breakdown Voltage ⁽³⁾ | $I_T = 1.0\text{ mA}$ | | V_{BR} | 25.7 | 27.0 | 28.4 V |
| | Stand-off Voltage | | | V_{WM} | - | 23.1 | - V |
| | Maximum Reverse Leakage | Rated V_{WM} | | I_D | - | - | 0.5 μA |
| | Maximum Clamping Voltage | $I_{PPM} = 5.3\text{ A}$, 10/1000 μs waveform | | V_C | - | - | 37.5 V |
| | Typical junction capacitance | 0 V | | C_J | | 330 | pF |
| | Typical junction capacitance | 23.1 V | | C_J | | 95 | pF |

Notes

- (1) Pulse test: 300 μs pulse width, 1 % duty cycle
 (2) Pulse test: pulse width $\leq 5\text{ ms}$
 (3) Pulse test: $t_p \leq 50\text{ ms}$

| IMMUNITY TO ELECTRICAL STATIC DISCHARGE TO THE FOLLOWING STANDARDS ($T_A = 25\text{ }^{\circ}\text{C}$ unless otherwise noted) | | | | | |
|--|-----------------------------------|--|--------|-------|---------|
| STANDARD | TEST TYPE | TEST CONDITIONS | SYMBOL | CLASS | VALUE |
| AEC-Q101-001 | Human body model (contact mode) | $C = 100\text{ pF}$, $R = 1.5\text{ k}\Omega$ | V_C | H3B | > 8 kV |
| AEC-Q101-005 | Charged device model (CDM) | $V = 500\text{ V}$ | | C3 | > 1 kV |
| IEC 61000-4-2 ⁽²⁾ | Contact mode | $C = 150\text{ pF}$, $R = 330\text{ }\Omega$ | | 4 | > 8 kV |
| | Air-discharge mode ⁽¹⁾ | $C = 150\text{ pF}$, $R = 330\text{ }\Omega$ | | 4 | > 15 kV |

Notes

- (1) Immunity to IEC 61000-4-2 air discharge mode has a typical performance > 30 kV
 (2) System ESD standard

| THERMAL CHARACTERISTICS ($T_A = 25\text{ }^{\circ}\text{C}$ unless otherwise noted) | | | | |
|--|--------------------------|------|------|----------------------|
| PARAMETER | SYMBOL | TYP. | MAX. | UNIT |
| Thermal resistance per diode | $R_{\theta JA}^{(1)(2)}$ | 80 | - | $^{\circ}\text{C/W}$ |
| | $R_{\theta JM}^{(3)}$ | 3.0 | 4.0 | |

Notes

- (1) The heat generated must be less than thermal conductivity from junction-to-ambient: $dP_D/dT_J < 1/R_{\theta JA}$
 (2) Thermal resistance junction-to-ambient to follow JEDEC[®] 51-2A, device mounted on FR4 PCB, 2 oz., standard footprint
 (3) Thermal resistance junction-to-mount to follow JEDEC[®] 51-14 transient dual interface test method (TDIM)

| ORDERING INFORMATION (Example) | | | | |
|--------------------------------|-----------------|------------------------|---------------|------------------------------------|
| PREFERRED P/N | UNIT WEIGHT (g) | PREFERRED PACKAGE CODE | BASE QUANTITY | DELIVERY MODE |
| R3T2FPHM3/I ⁽¹⁾ | 0.10 | I | 6000 | 13" diameter plastic tape and reel |

Note

- (1) AEC-Q101 qualified

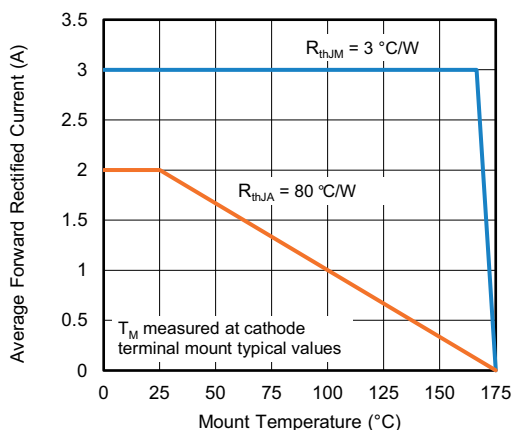
RATINGS AND CHARACTERISTICS CURVES FOR RECTIFIERS ($T_A = 25\text{ }^{\circ}\text{C}$ unless otherwise noted)


Fig. 1 - Maximum Forward Derating Curve

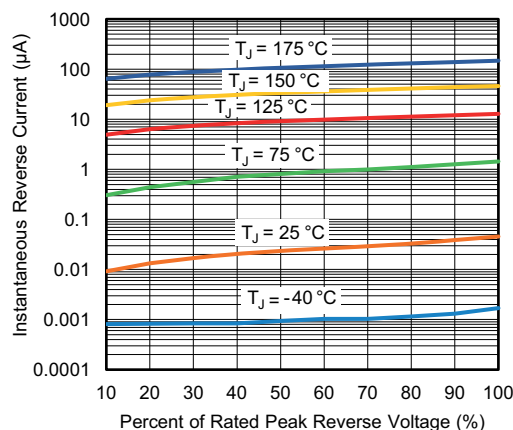


Fig. 4 - Typical Reverse Leakage Characteristics

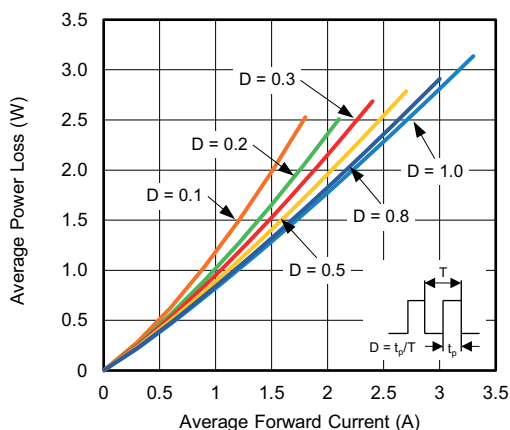


Fig. 2 - Forward Power Loss Characteristics

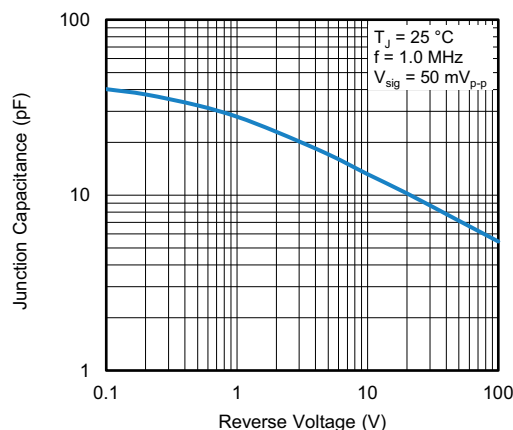


Fig. 5 - Typical Junction Capacitance

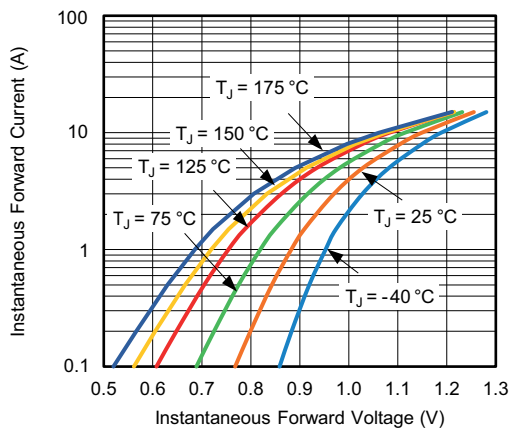


Fig. 3 - Typical Instantaneous Forward Characteristics

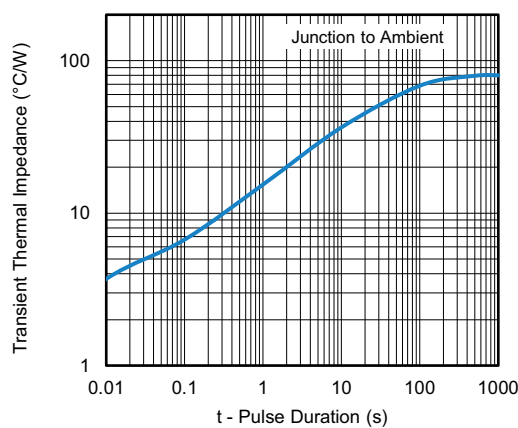


Fig. 6 - Typical Transient Thermal Impedance

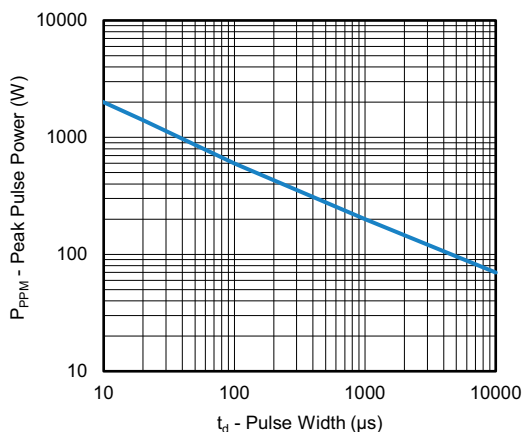
RATINGS AND CHARACTERISTICS CURVES FOR TVS ($T_A = 25\text{ }^{\circ}\text{C}$ unless otherwise noted)


Fig. 7 - Peak Pulse Power Derating Curve

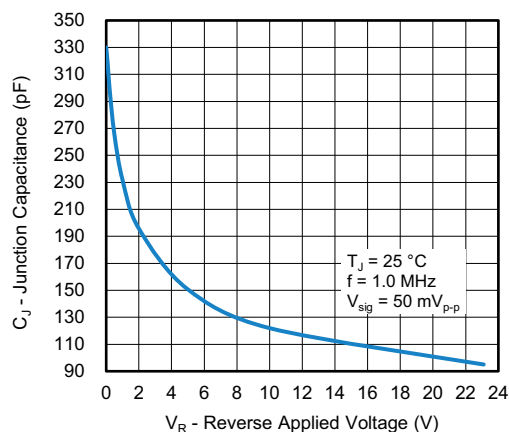


Fig. 9 - Typical Junction Capacitance

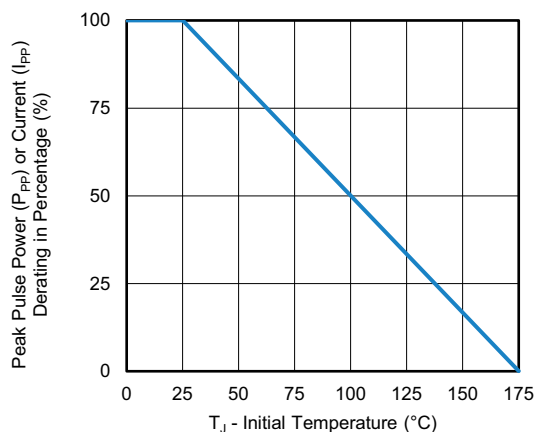


Fig. 8 - Pulse Power or Current vs. Initial Junction Temperature

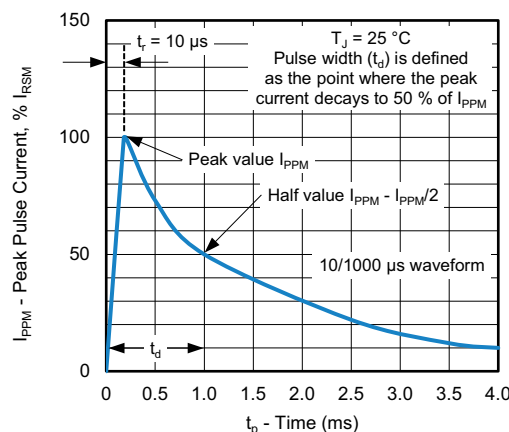
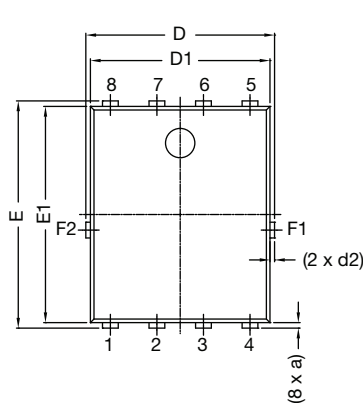
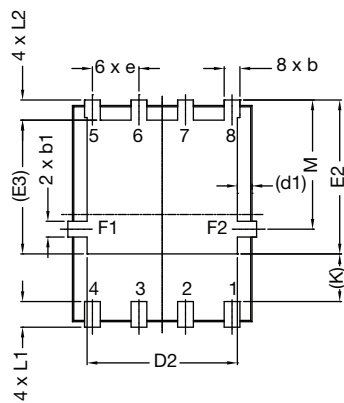
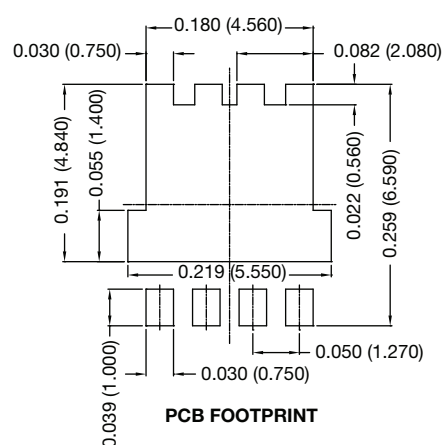
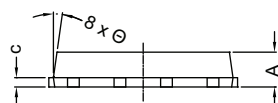


Fig. 10 - Pulse Waveform

**PACKAGE OUTLINE DIMENSIONS** in inches (millimeters)**FlatPAK 5 x 6****TOP VIEW****BOTTOM VIEW****PCB FOOTPRINT****SIDE VIEW**

| DIM. | INCHES | | | MILLIMETERS | | |
|------|-----------|-------|-------|-------------|-------|------|
| | MIN. | NOM. | MAX. | MIN. | NOM. | MAX. |
| A | 0.035 | 0.039 | 0.043 | 0.89 | 0.99 | 1.09 |
| (a) | - | 0.006 | - | - | 0.15 | - |
| b | 0.013 | 0.017 | 0.020 | 0.32 | 0.43 | 0.52 |
| b1 | 0.013 | 0.017 | 0.020 | 0.32 | 0.43 | 0.52 |
| c | 0.008 | - | 0.014 | 0.20 | - | 0.35 |
| D | 0.197 | 0.203 | 0.209 | 5.00 | 5.15 | 5.30 |
| D1 | 0.189 | 0.193 | 0.197 | 4.80 | 4.90 | 5.00 |
| D2 | 0.154 | 0.161 | 0.169 | 3.90 | 4.10 | 4.30 |
| (d1) | - | 0.016 | - | - | 0.40 | - |
| (d2) | - | 0.005 | - | - | 0.125 | - |
| E | 0.238 | 0.244 | 0.250 | 6.05 | 6.20 | 6.35 |
| E1 | 0.228 | 0.232 | 0.236 | 5.80 | 5.90 | 6.00 |
| E2 | 0.157 | 0.165 | 0.173 | 4.00 | 4.20 | 4.40 |
| (E3) | - | 0.144 | - | - | 3.65 | - |
| e | 0.050 BSC | | | 1.27 BSC | | |
| (K) | 0.039 | - | - | 1.00 | - | - |
| L1 | 0.019 | - | 0.043 | 0.48 | - | 1.10 |
| L2 | 0.012 | - | 0.031 | 0.30 | - | 0.80 |
| M | 0.128 | 0.138 | 0.148 | 3.25 | 3.50 | 3.75 |
| θ | 0° | - | 10° | 0° | - | 10° |

Notes

- Dimensioning and tolerancing per ASME Y14.5-2009
- Dimensions D1 and E1 do not include mold flash or gate burrs
- Dimension (XX) means reference only



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